	Tentative	DA36103E	
		Total pages	page

DA36103E

Silicon epitaxial planar type

For high speed switching

Marking Symbol : 24

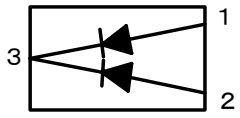
Package Code : ML3-N4-B

Absolute Maximum Ratings Ta = 25 °C

Parameter		Symbol	Rating	Unit
Reverse voltage		VR	80	V
Maximum peak reverse voltage		VRM	80	V
Forward current	Single	IF	100	mA
	Double		150	
Peak forward current	Single	IFM	225	mA
	Double		340	
Non-repetitive peak forward surge current *1	Single	IFSM	500	mA
	Double		750	
Junction temperature		Tj	150	°C
Storage temperature		Tstg	-55 to +150	°C

Note: 1. *1 t = 1 s

Internal Connection

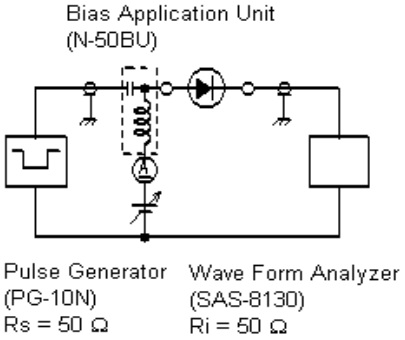


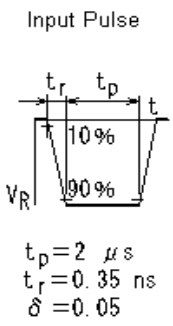
Pin name		
	1.	Anode1
	2.	Anode2
	3.	Cathode1
		Cathode2

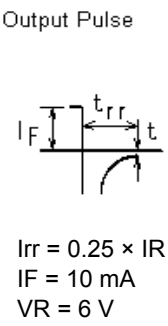
Electrical Characteristics Ta = 25 °C±3 °C

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	VF	IF = 100 mA			1.2	V
Reverse voltage	VR	IR = 100 µA	80			V
Reverse current	IR	VR = 80V			100	nA
Terminal capacitance	Ct	VR = 0 V, f = 1 MHz		2	15	pF
Reverse recovery time *1	trr	IF = 10mA, VR = 6V Irr = 0.25 x IR		2	10	ns

Note: 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.
2. Absolute frequency of input and output is 100 MHz.
3. *1 trr test circuit







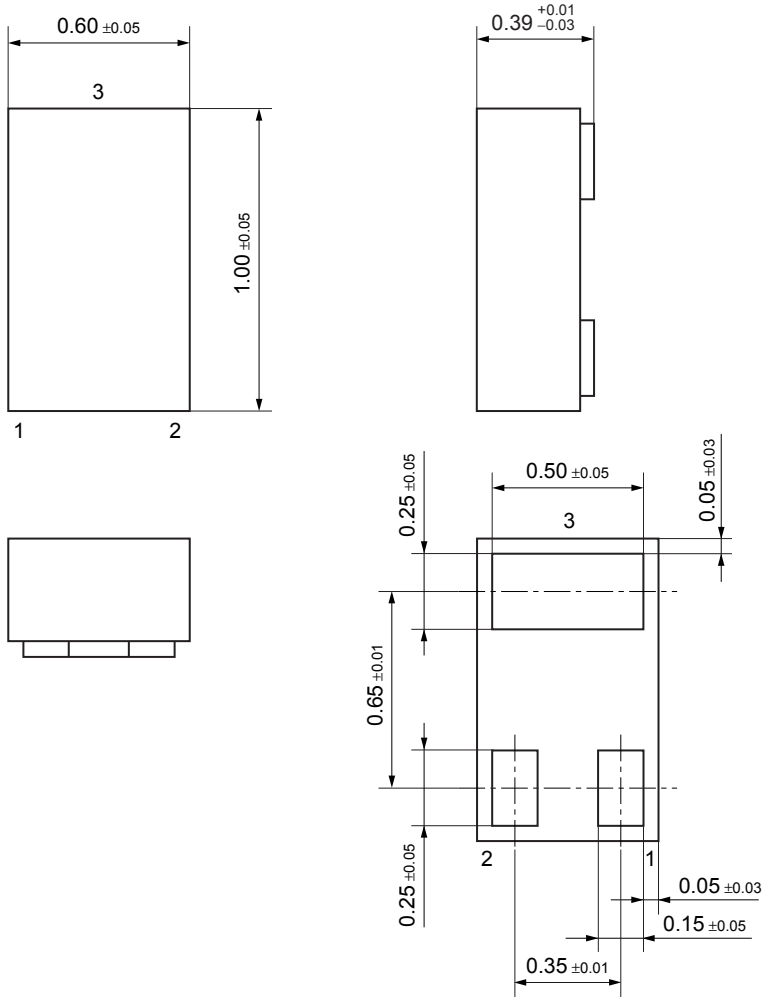
Packing

Embossed type (Thermo-compression sealing) : 10 000 pcs / reel

2010.4.7	2010.7.27	
Prepared	Revised	

ML3-N4-B

Unit: mm



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